

TOSHIBA RECTIFIER SILICON DIFFUSED JUNCTION TYPE

U2BC44, U2GC44, U2JC44

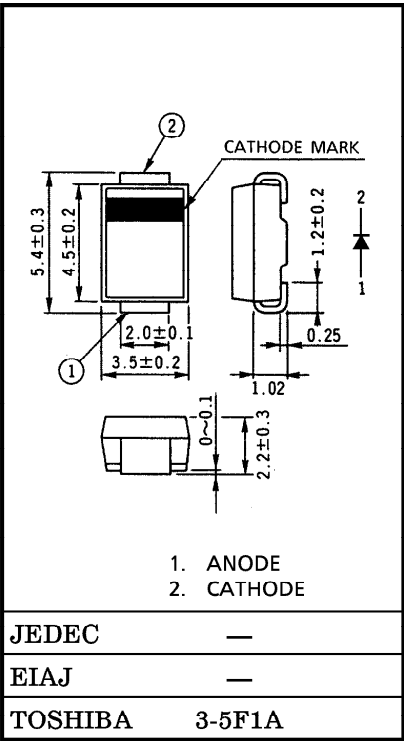
GENERAL PURPOSE RECTIFIER APPLICATIONS

Unit in mm

- Repetitive Peak Reverse Voltage :  $V_{RRM}=100\sim600V$
- Average Forward Current :  $I_F(AV)=2.0A$
- Mini Plastic Mold Package

MAXIMUM RATINGS

CHARACTERISTIC		SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	U2BC44	$V_{RRM}$	100	V
	U2GC44		400	
	U2JC44		600	
Average Forward Current	On Ceramic Substrate	$I_F(AV)$	2.0 ( $T_a=45^{\circ}C$ )	A
	On Glass-epoxy Substrate		1.3 ( $T_a=25^{\circ}C$ )	
Peak One Cycle Surge Forward Current (Non-Repetitive)		$I_{FSM}$	80 (50Hz) 88 (60Hz)	A
Junction Temperature Range		$T_j$	$-40\sim150$	$^{\circ}C$
Storage Temperature Range		$T_{stg}$	$-40\sim150$	$^{\circ}C$



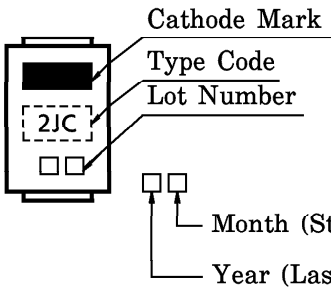
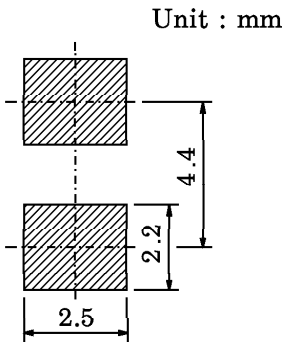
ELECTRICAL CHARACTERISTICS ( $T_a=25^{\circ}C$ )

Weight : 0.1g

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Forward Voltage	$V_{FM}$	$I_{FM}=2.0A$	—	—	1.2	V
Repetitive Peak Reverse Current	$I_{RRM}$	$V_{RRM}=\text{Rated}$	—	—	10	$\mu A$
Thermal Resistance	$R_{th(j-a)}$	DC On ceramic substrate	—	—	50	$^{\circ}C/W$
		On glass-epoxy substrate	—	—	110	$^{\circ}C/W$

STANDARD SOLDERING PAD

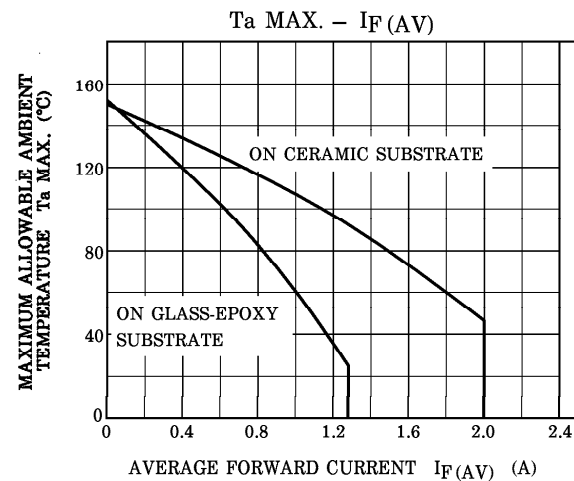
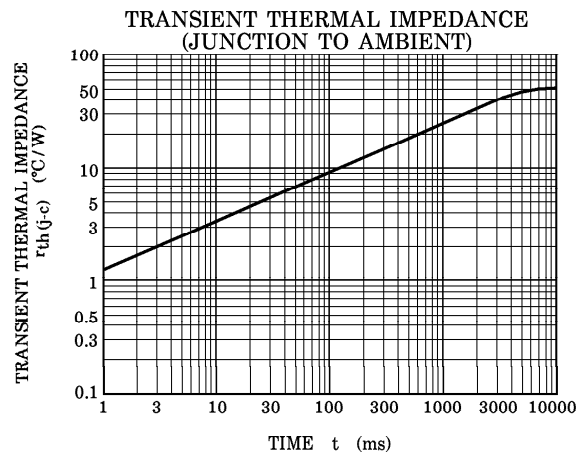
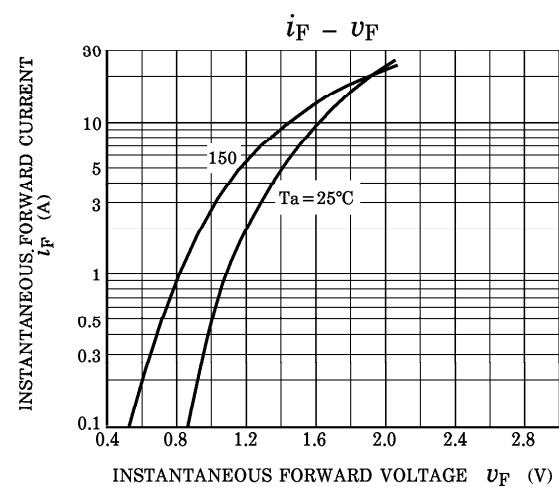
MARKING



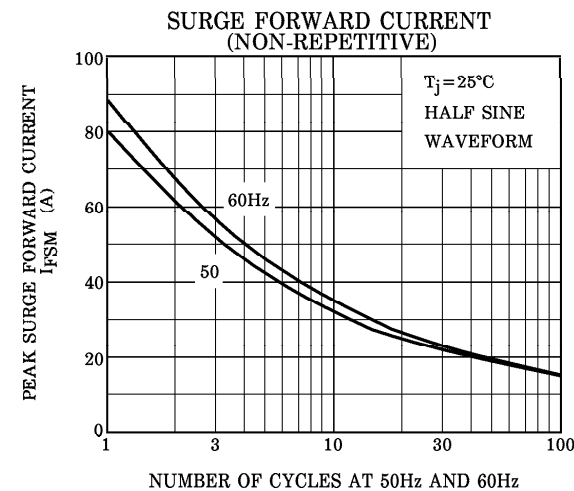
CODE	TYPE
2BC	U2BC44
2GC	U2GC44
2JC	U2JC44

961001EAA2

● TOSHIBA is continually working to improve the quality and the reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to observe standards of safety, and to avoid situations in which a malfunction or failure of a TOSHIBA product could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent products specifications. Also, please keep in mind the precautions and conditions set forth in the TOSHIBA Semiconductor Reliability Handbook.



	ON CERAMIC SUBSTRATE	ON GLASS-EPOXY SUBSTRATE
Soldering land : a	2.2×2.5mm	6mm
Substrate size : b	50mm	50mm
Substrate thickness : c	0.64t	1.6t



961001EAA2'

- The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any intellectual property or other rights of TOSHIBA CORPORATION or others.
- The information contained herein is subject to change without notice.